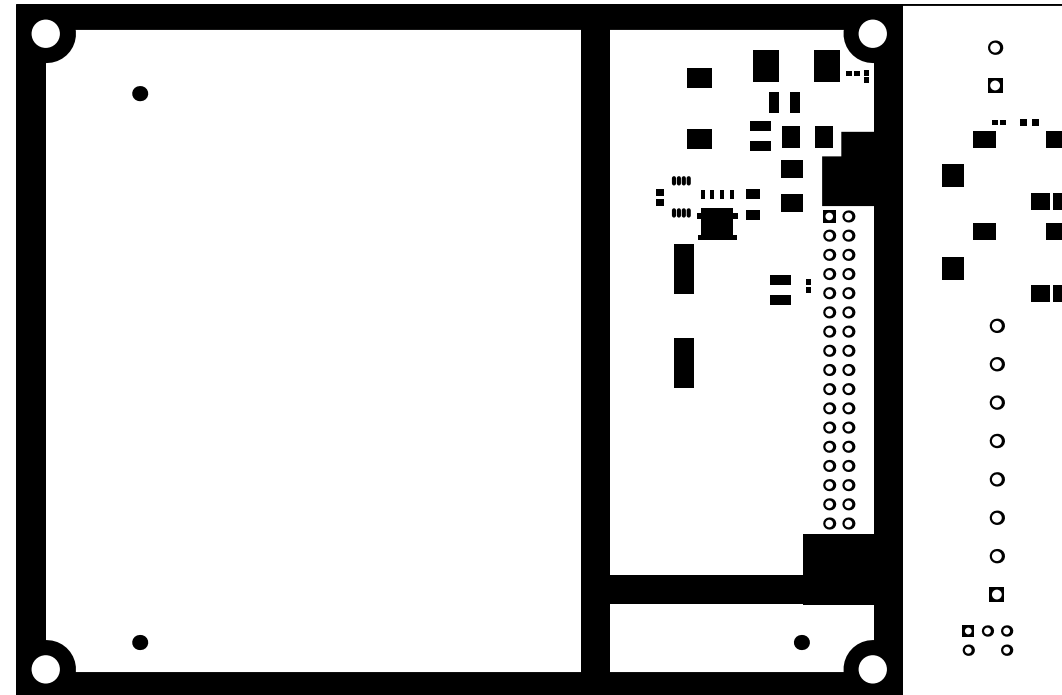
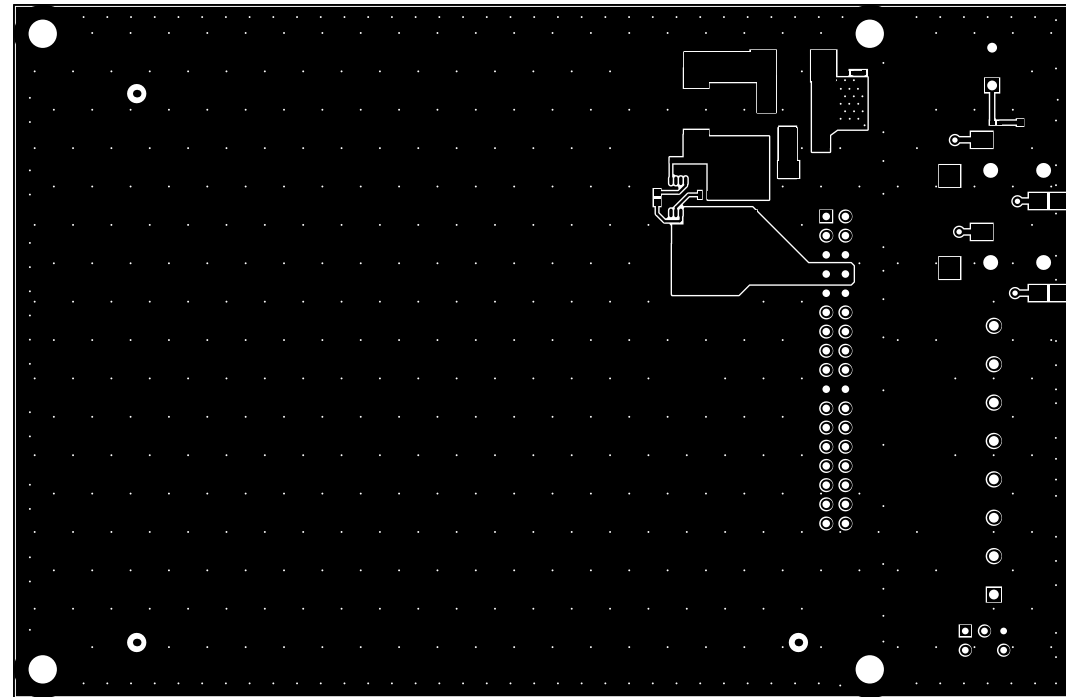


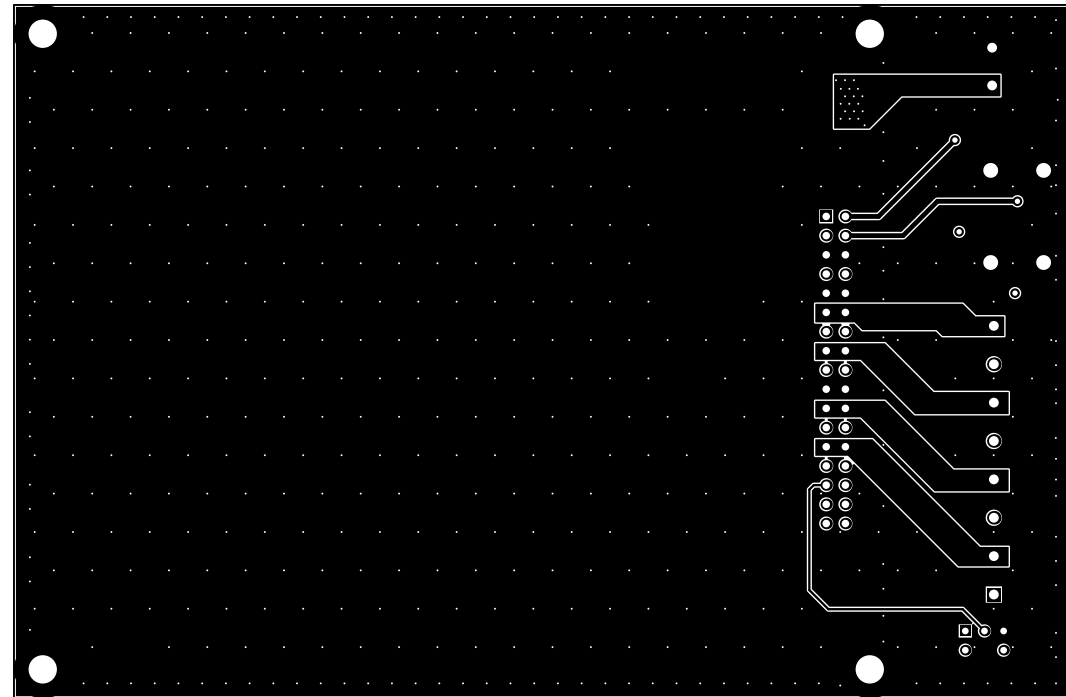
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00743_2	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00743		
PLOT NAME = Top Overlay	GENERATED : 5/23/2017	2:08:21 PM	TEXAS INSTRUMENTS



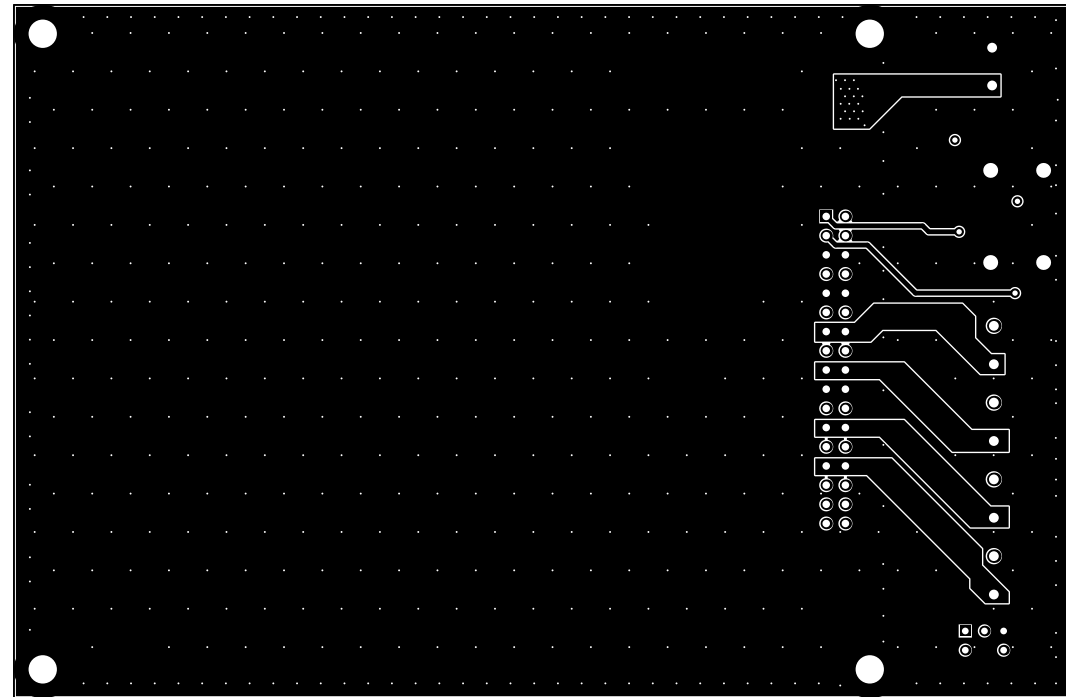
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00743_2	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00743		
PLOT NAME = Top Solder Mask	GENERATED : 5/23/2017 2:08:22 PM	TEXAS INSTRUMENTS	



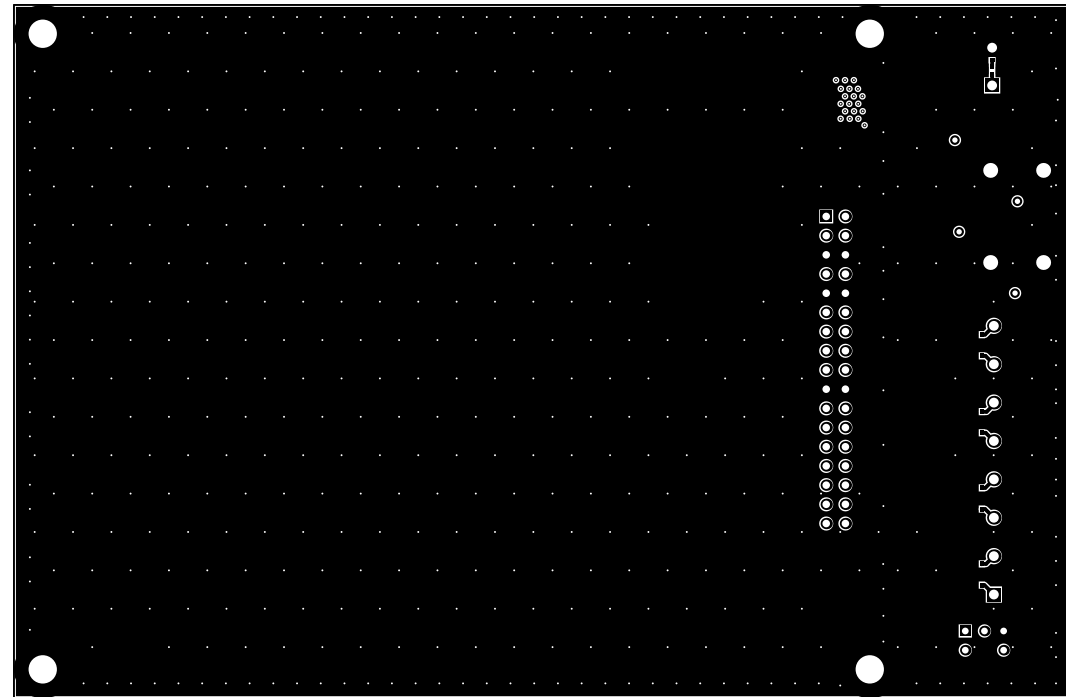
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00743_2	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00743		
PLOT NAME = Top Layer	GENERATED : 5/23/2017 2:08:24 PM	TEXAS INSTRUMENTS	



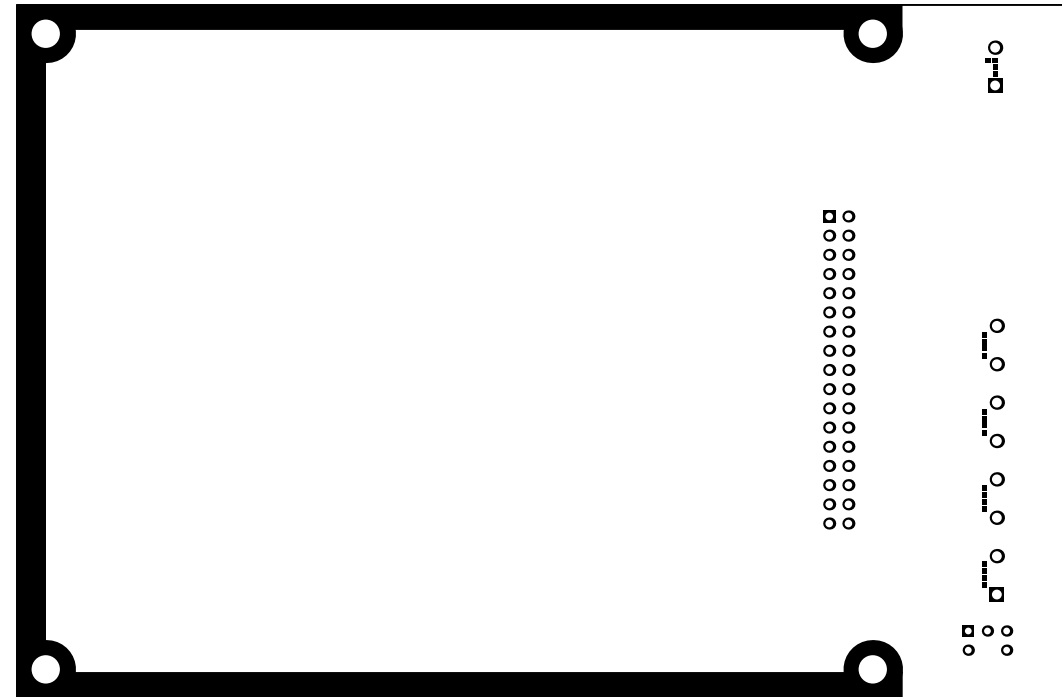
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00743_2	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00743		
PLOT NAME = Signal Layer 1	GENERATED : 5/23/2017 2:08:25 PM	TEXAS INSTRUMENTS	



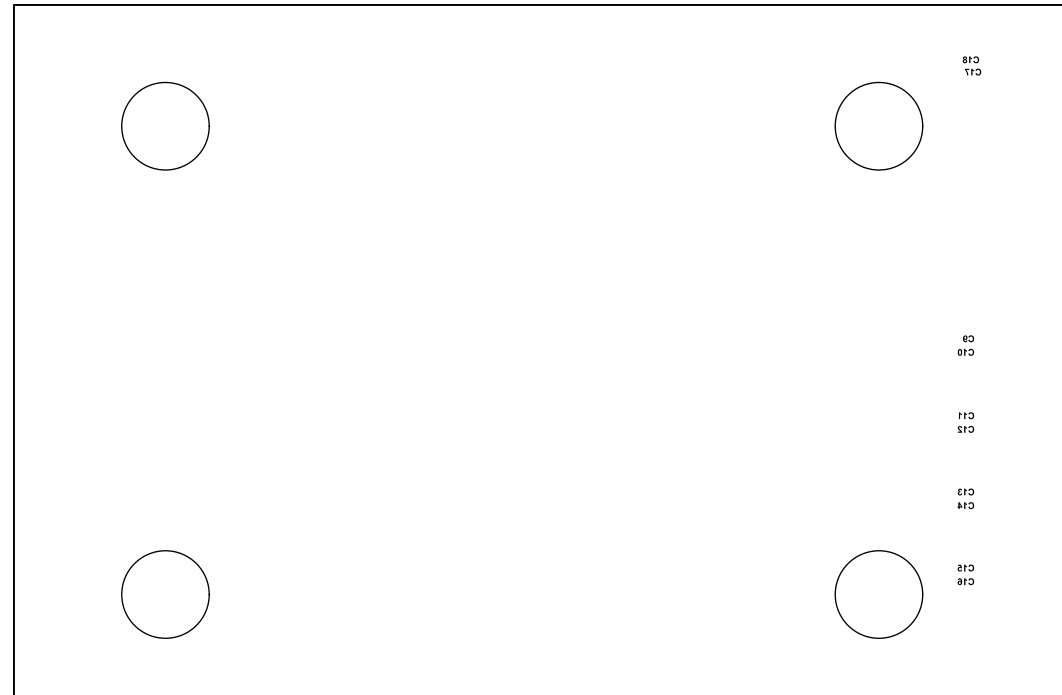
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00743_2	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00743		
PLOT NAME = Signal Layer 2	GENERATED : 5/23/2017 2:08:27 PM	TEXAS INSTRUMENTS	



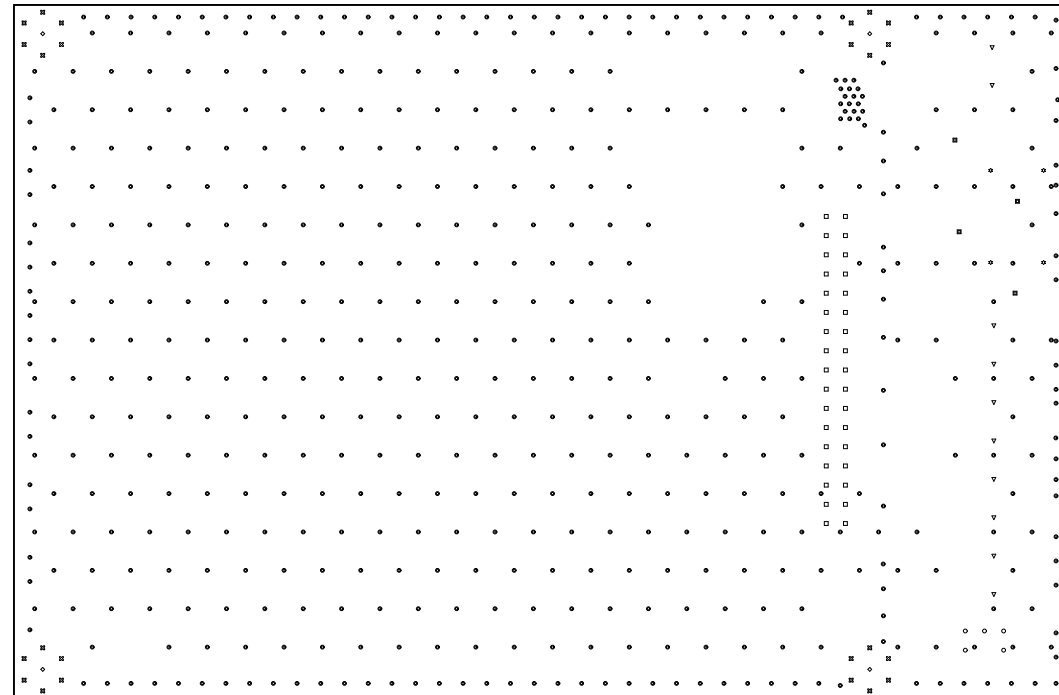
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00743_2	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00743		
PLOT NAME = Bottom Layer	GENERATED : 5/23/2017 2:08:28 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00743_2	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00743		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/23/2017 2:08:30 PM	TEXAS INSTRUMENTS	

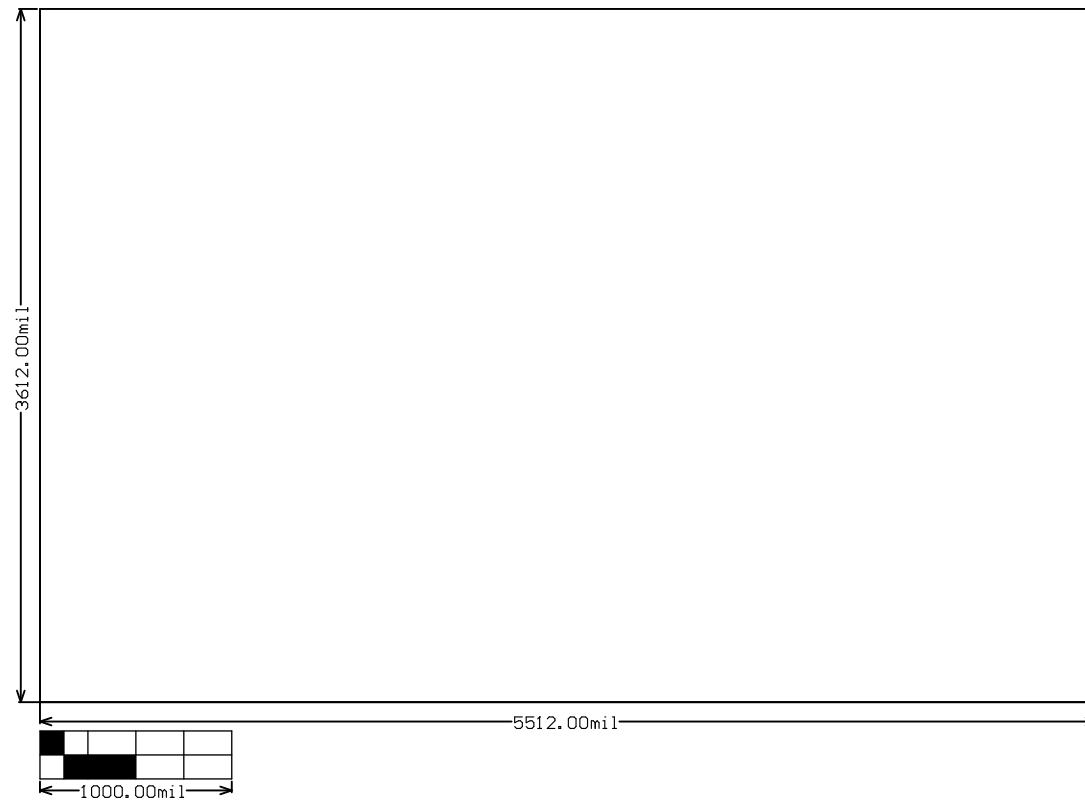


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00743_2	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00743		
PLOT NAME = Bottom Overlay	GENERATED : 5/23/2017 2:08:31 PM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
⚙	4	63.00mil (1.600mm)	NPTH	Round	Top Layer - Bottom Layer	
●	534	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	24	19.69mil (0.500mm)	PTH	Round	Top Layer - Bottom Layer	
■	4	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
○	5	35.04mil (0.890mm)	PTH	Round	Top Layer - Bottom Layer	
□	34	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
▽	10	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
◇	4	147.64mil (3.750mm)	PTH	Round	Top Layer - Bottom Layer	
	619 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00743_2	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00743		
PLOT NAME = Drill Drawing	GENERATED : 5/23/2017	2:08:32 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA00743_2	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-00743		
PLOT NAME = Board Dimensions	GENERATED : 5/23/2017 2:08:34 PM	TEXAS INSTRUMENTS	

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